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Liu et al.

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(54) **METHOD OF MAKING A STRUCTURE**

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H01L 27/06 (2006.01)

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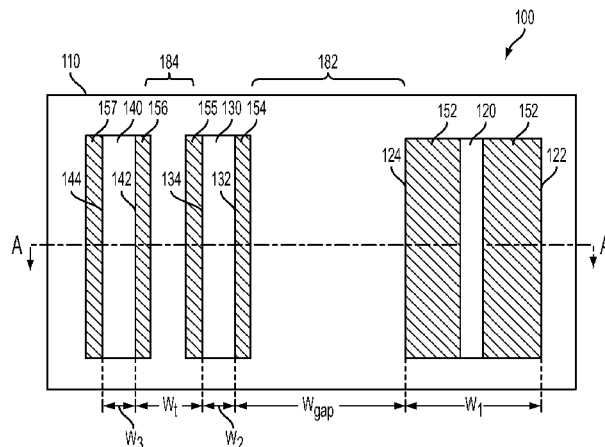
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(57) **ABSTRACT**

A method of making a structure includes forming a first supporting member over a substrate, the first supporting member comprising a first material and having a first width defined along a reference plane. The method further includes forming a second supporting member over the substrate, the second supporting member having a second width defined along the reference plane, and the first supporting member and the second supporting member being separated by a gap region. The first width is at least 10 times the second width, and a gap width of the gap region being from 5 to 30 times the second width.

20 Claims, 5 Drawing Sheets



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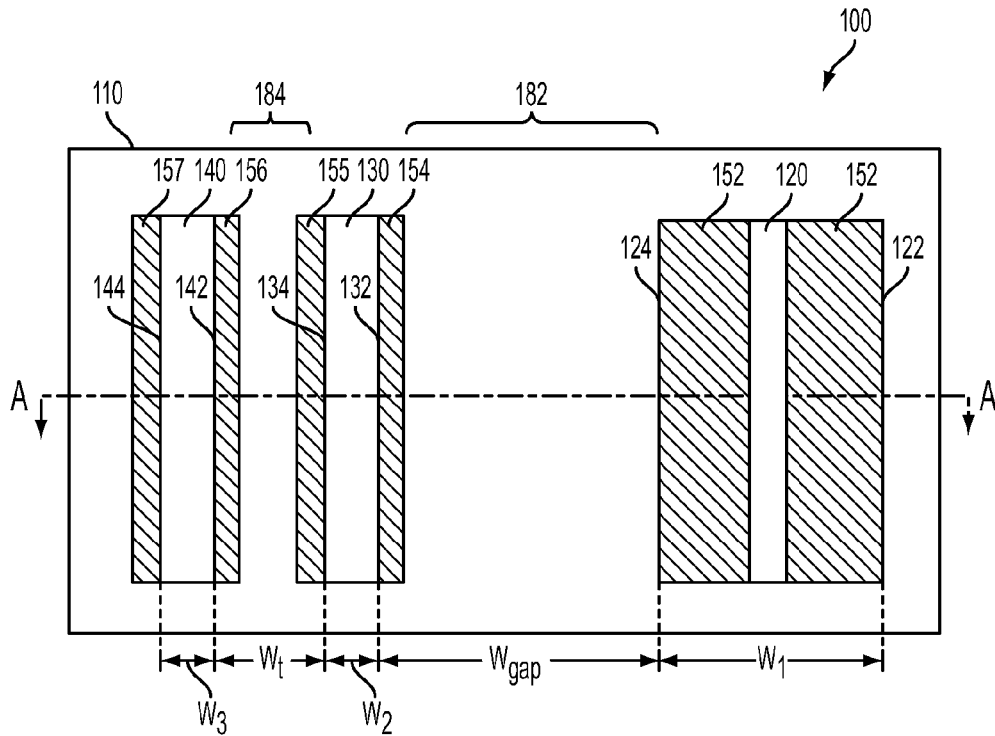


FIG. 1A

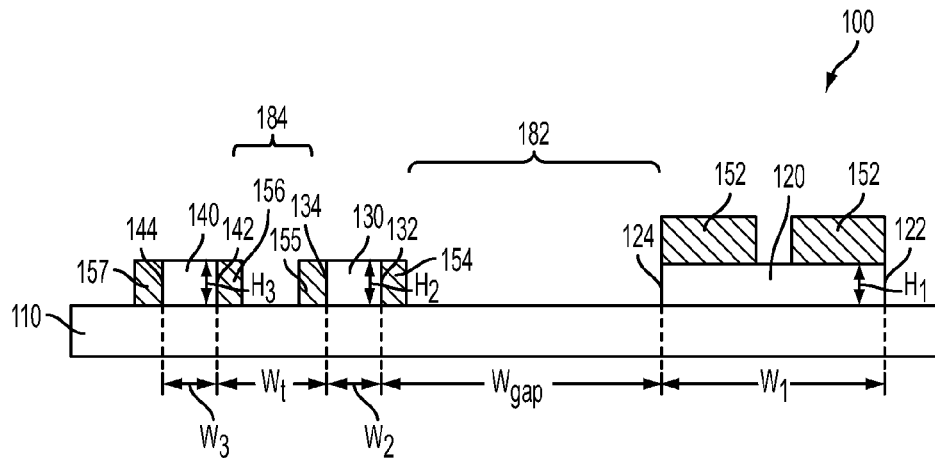


FIG. 1B

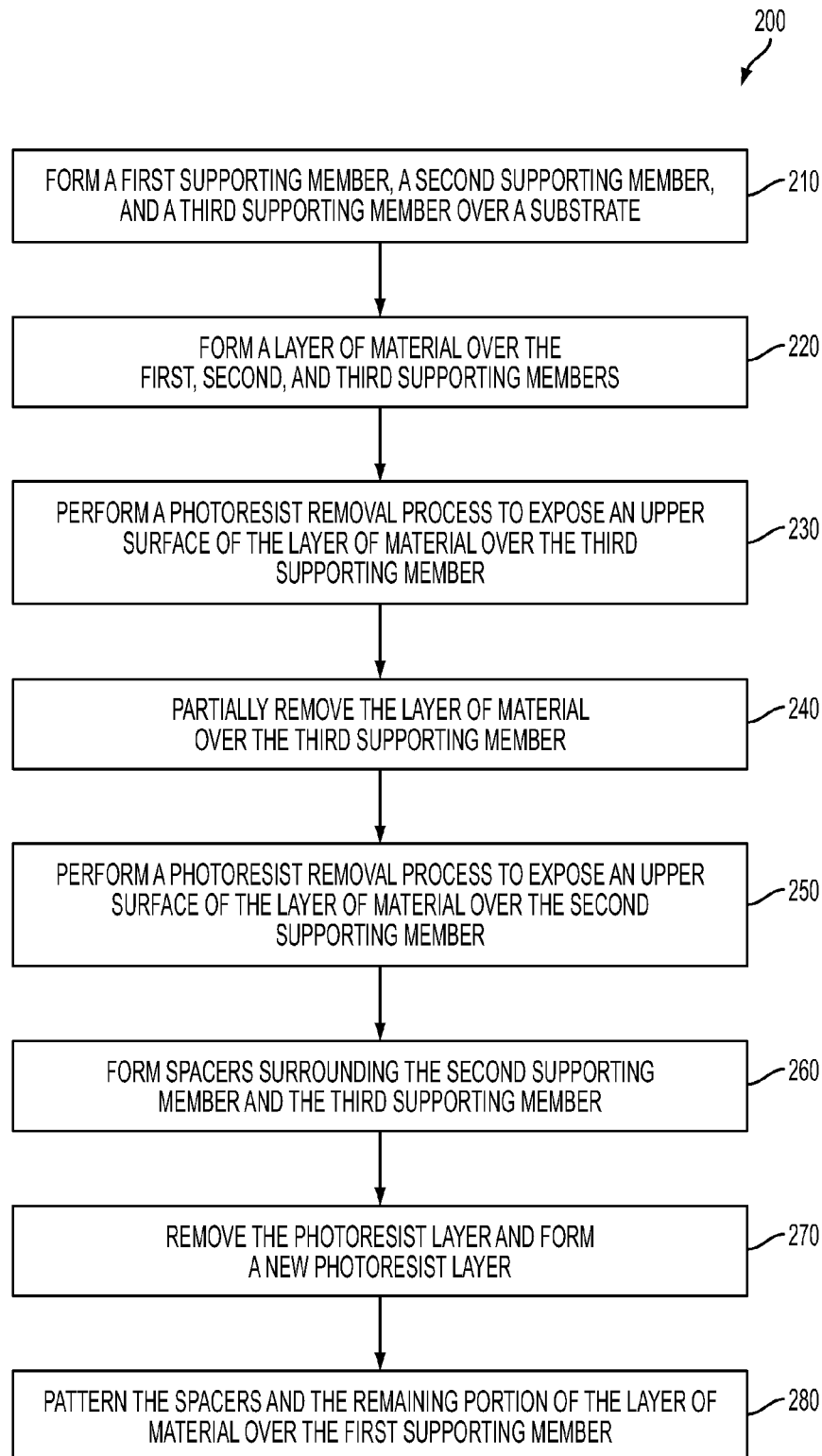


FIG. 2

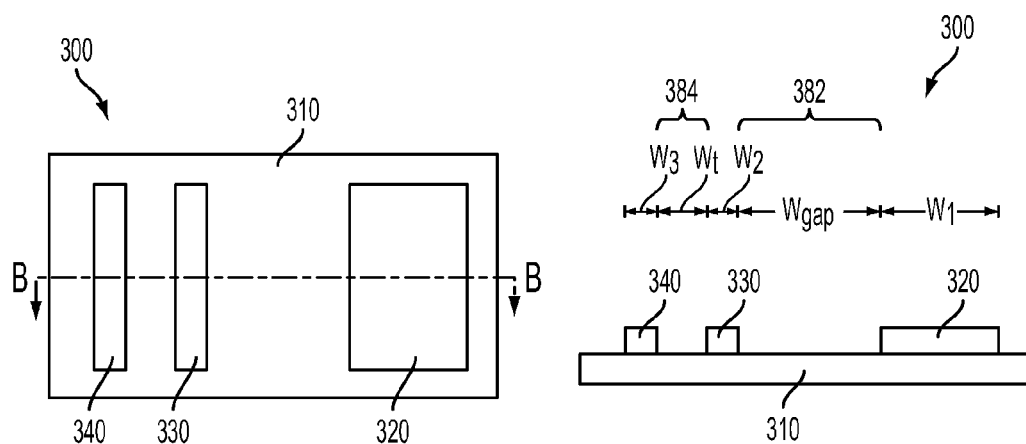


FIG. 3A

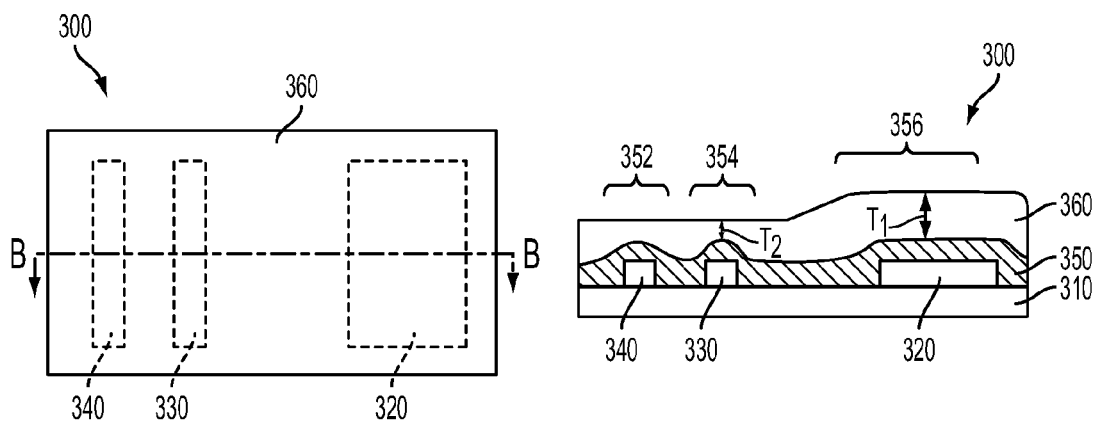


FIG. 3B

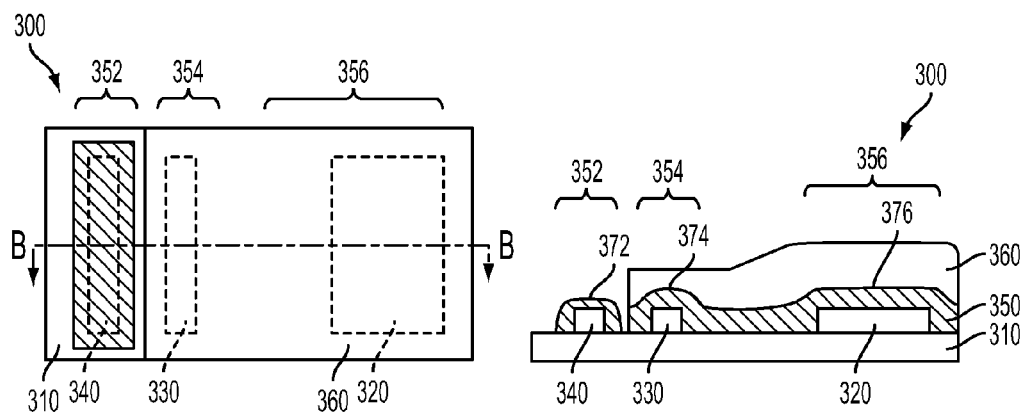


FIG. 3C

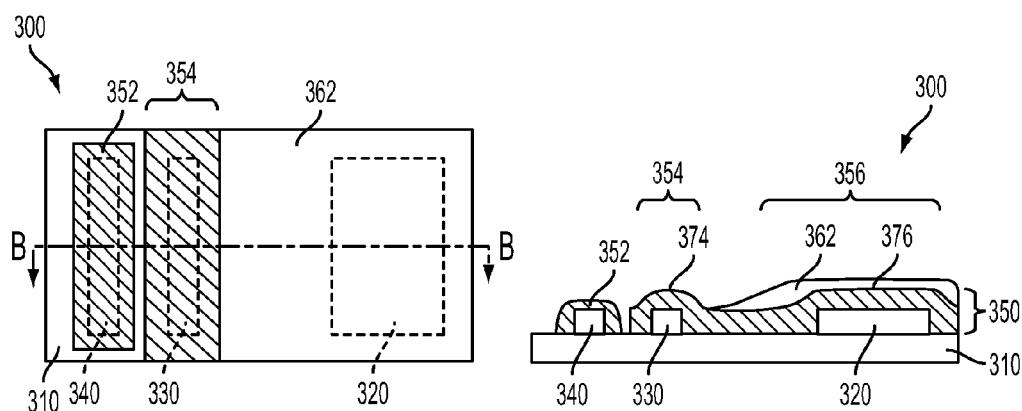


FIG. 3D

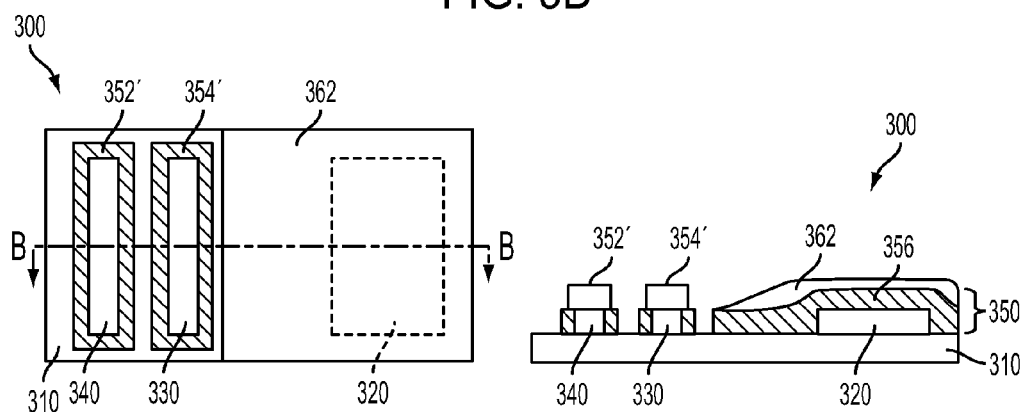


FIG. 3E

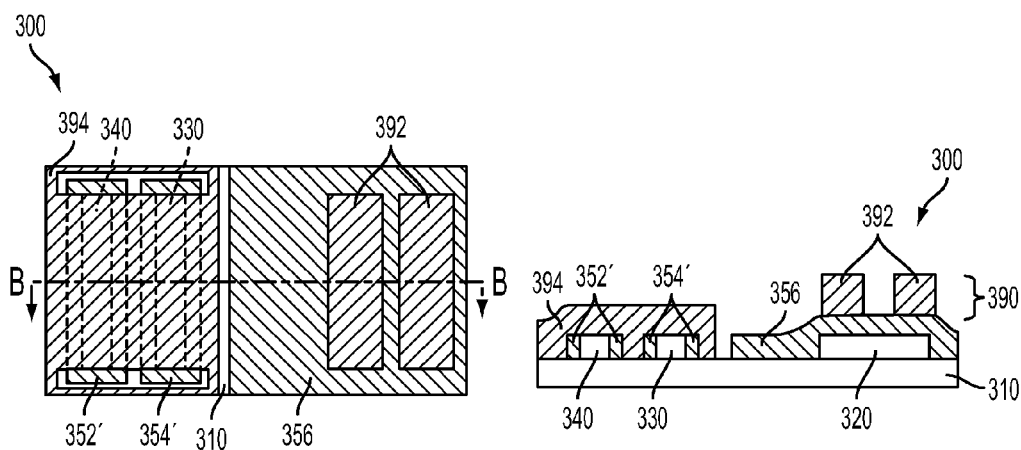


FIG. 3F

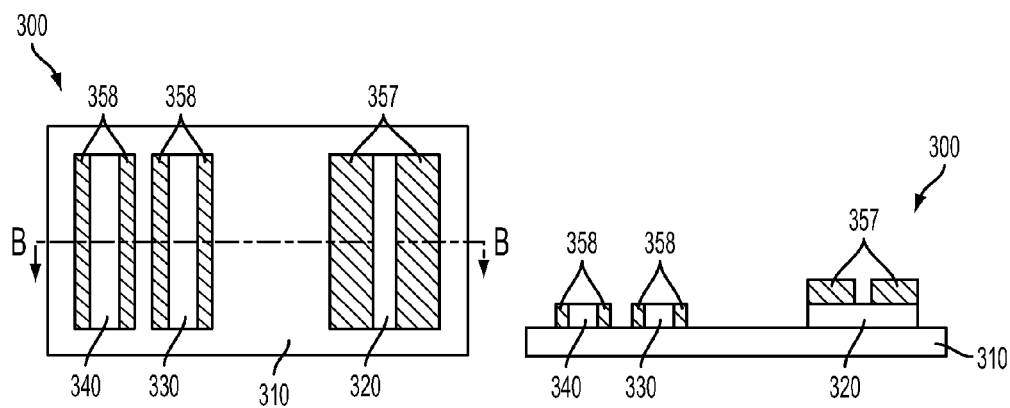


FIG. 3G

METHOD OF MAKING A STRUCTURE

PRIORITY CLAIM

The present application is a divisional of U.S. application Ser. No. 13/370,828, filed Feb. 10, 2012, which is incorporated herein by reference in its entirety.

BACKGROUND

In the course of integrated circuit (IC) evolution, functional density (i.e., the number of interconnected devices per chip area) has generally increased while geometry size (i.e., the smallest component (or line) that can be created using a fabrication process) has decreased. This scaling-down process generally provides benefits by increasing production efficiency and lowering associated costs. Such scaling-down also produces a relatively high power dissipation value, which may be addressed by using low power dissipation devices such as complementary metal-oxide-semiconductor (CMOS) devices. Meanwhile, some components and devices in an IC chip still have a relatively larger size for applications such as analog circuits or high-power circuits than those for applications such as digital circuits. Various manufacturing processes have been introduced to effectively components and devices having various sizes in a single IC chip.

DESCRIPTION OF THE DRAWINGS

One or more embodiments are illustrated by way of examples, and not by limitation, in the figures of the accompanying drawings, wherein elements having the same reference numeral designations represent like elements throughout and wherein:

FIG. 1A is a top view of a structure in accordance with one or more embodiments;

FIG. 1B is a cross-sectional view of the structure of FIG. 1A taken from line A in accordance with one or more embodiments;

FIG. 2 is a flow chart of a method of manufacturing a structure in accordance with one or more embodiments; and

FIGS. 3A-3G are top views and corresponding cross-sectional views of a structure at various manufacturing stages in accordance with one or more embodiments.

DETAILED DESCRIPTION

It is understood that the following disclosure provides many different embodiments, or examples, for implementing different features of the disclosure. Specific examples of components and arrangements are described below to simplify the present disclosure. These are, of course, examples and are not intended to be limiting. In accordance with the standard practice in the industry, various features in the drawings are not drawn to scale and are used for illustration purposes only.

The formation of a feature on, connected to, and/or coupled to another feature in the present disclosure that follows may include embodiments in which the features are formed in direct contact, and may also include embodiments in which additional features may be formed interposing the features, such that the features may not be in direct contact.

In addition, spatially relative terms, for example, “lower,” “upper,” “horizontal,” “vertical,” “above,” “below,” “up,” “down,” “top,” “bottom,” etc. as well as derivatives thereof (e.g., “horizontally,” “downwardly,” “upwardly,” etc.) are

used for ease of the present disclosure of one features relationship to another feature. The spatially relative terms are intended to cover different orientations of the device including the features.

FIG. 1A is a top view of a structure **100** in accordance with one or more embodiments. FIG. 1B is a cross-sectional view of the structure **100** of FIG. 1A taken from line A in accordance with one or more embodiments. The structure **100** includes a substrate **110**, a first supporting member **120** having side walls **122** and **124**, a second supporting member **130** having side walls **132** and **134**, and a third supporting member **140** having side walls **142** and **144**. The first, second, and third supporting members **120**, **130**, and **140** are over the substrate **110**. In at least one embodiment, the first supporting member **120**, the second supporting member **130**, and the third supporting member **140** are parallel with one another. In some embodiments, the structure **100** further includes one or more patterned features **152** over the first supporting member **120**, one or more strips **154** or **155** on side walls **132** or **134** of the second supporting member **130**, and one or more strips **156** and **157** on side walls **142** or **144** of the third supporting member **140**. In some embodiments, the patterned features **152** are conductive features, and the strips **154**, **155**, **156**, and **157** are conductive strips. In some embodiments, the structure **100** is a semiconductor structure.

In some embodiments, the substrate **110** includes: an elemental semiconductor such as silicon or germanium in crystal, polycrystalline, or an amorphous structure; a compound semiconductor including silicon carbide, gallium arsenide, gallium phosphide, indium phosphide, indium arsenide, and/or indium antimonide; an alloy semiconductor including SiGe, GaAsP, AlInAs, AlGaAs, GaInAs, GaInP, and/or GaInAsP; or combinations thereof. In at least one embodiment, the substrate **110** is an alloy semiconductor substrate having a gradient SiGe feature in which the respective Si and Ge concentrations change from one ratio at one location to another ratio at another location of the gradient SiGe feature. In another embodiment, the alloy SiGe is formed over a silicon substrate. In yet another embodiment, a SiGe substrate is strained. In some embodiments, the semiconductor substrate **110** has a semiconductor-on-insulator (SOI) structure. In some embodiments, the semiconductor substrate **110** includes a doped epitaxial layer or a buried layer. In other examples, the compound semiconductor substrate has a multilayer structure, or the substrate includes a multilayer compound semiconductor structure.

The first supporting member **120** has a first width W_1 defined as a distance between the side walls **122** and **124** at the points of intersection of a reference cross-sectional plane containing the line A and being perpendicular to a planar direction of the substrate **110**. The first supporting member **120** also has a first height H_1 measurable along the reference cross-sectional plane. The second supporting member **130** has a second width W_2 defined as a distance between the side walls **132** and **134** at the points of intersection of the reference cross-sectional plane. The second supporting member **130** also has a second height H_2 measurable along the reference cross-sectional plane. The third supporting member **140** has a third width W_3 defined as a distance between the side walls **142** and **144** at the points of intersection of the reference cross-sectional plane. The third supporting member **140** also has a third height H_3 measurable along the reference cross-sectional plane.

The first supporting member **120** and the second supporting member **130** are separated by a gap region **182**. The gap region **182** has a gap width W_{gap} defined as a distance

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between the side wall **124** and the sidewall **132** along the reference cross-sectional plane. Also, the second supporting member **130** and the third supporting member **140** are separated by a trench region **184**. The trench region **184** has a trench width W_t , defined as a distance between the side wall **134** and the sidewall **142** along the reference cross-sectional plane.

In some embodiments, the gap region **180** is substantially free of any feature that interferes with formation of the photoresist layer **360** as depicted in FIG. 3B.

In some embodiments, the first width W_1 is at least 10 times the second width W_2 , and the gap width W_{gap} of the gap region **180** ranges from 5 to 30 times the second width W_2 . In some embodiments, the second width W_2 ranges from 0.8 to 1.2 times the third width W_3 . In some embodiments, the trench width W_t ranges from 2.0 to 3.0 times the second width W_2 .

In some embodiments, the second width W_2 is equal to or less than 100 nm. In at least one embodiment, the second width W_2 ranges from 30 nm to 90 nm, the first width W_1 ranges from 300 nm to 900 nm, and the gap width W_{gap} ranges from 200 nm to 1,000 nm.

In some embodiments, the first height H_1 ranges from 30 nm to 90 nm. In some embodiments, the second height H_2 ranges from 30 nm to 90 nm. In some embodiments, the third height H_3 ranges from 30 nm to 90 nm.

The first supporting member **120** is not limited to any particular size. In some embodiments, when viewed from the top as in FIG. 1A, the first supporting member **120** has a dimension ranging from 300 nm to 30,000 nm. In some embodiments, the range is from 500 nm to 2,000 nm or from 700 nm to 1,500 nm.

The second or third supporting members **130** or **140** are not limited to any particular size. In some embodiments, when viewed from the top as in FIG. 1A, the second supporting member **130** or the third supporting member **140** independently has a length ranging from 300 nm to 30,000 nm. In some embodiments, the range is from 500 nm to 2,000 nm or from 700 nm to 1,500 nm.

The first supporting member **120** is not limited to any particular shape. In some embodiments, the first supporting member **120** has a shape that lacks symmetry. In some embodiments, the first supporting member **120** has symmetry. In some embodiments, when viewed from the top, the first supporting member **120** has a shape that is rectangular, circular, or triangular.

The second or third supporting member **130** or **140** is not limited to any particular shape. In some embodiments, the second or third supporting member **130** or **140** has a shape that lacks symmetry. In some embodiments, the second or third supporting member **130** or **140** has symmetry. In some embodiments, when viewed from the top, the second or third supporting member **130** or **140** has a shape that is rectangular, circular, or triangular. In some embodiments, the second and third supporting members **130** and **140** have substantially the same shape. In some embodiments, the second and third supporting members **130** and **140** have different shapes.

In at least one embodiment, the first, second, and third supporting members **120**, **130**, and **140** are rectangular and arranged to be in parallel with one another.

In some embodiments, the third supporting member **140** is omitted.

In some embodiments, the first supporting member **120**, the second supporting member **130**, and the third supporting member **140** include a first material chosen from insulation materials. In some embodiments, the insulation materials

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include silicon dioxide or silicon nitride. In some embodiments, the first supporting member **120**, the second supporting member **130**, and the third supporting member **140** are formed of different materials.

In at least one embodiment, the patterned features **152** are usable for forming relatively larger components and devices such as capacitors, antennas, or resistors in an IC chip.

In some embodiments, the strips **154**, **155**, **156**, and **157** are usable for forming relatively smaller components and devices such as electrodes or dummy gate electrodes of transistors in the same IC chip.

In some embodiments, the patterned features **152** and the strips **154**, **155**, **156**, and **157** include a material chosen from conductive materials. In some embodiments, the conductive materials include polycrystalline silicon. In some embodiments, the patterned features **152** and the strips **154**, **155**, **156**, and **157** are formed of different materials. In some embodiments, the patterned features **152** and the strips **154**, **155**, **156**, and **157** include any suitable materials for use in semiconductor manufacturing, such as metallic materials, semiconductor materials, dielectric materials, or hardmask materials. In some embodiments, the patterned features **152** and the strips **154**, **155**, **156**, and **157** comprise silicon nitride, silicon oxide, nitride with carbide doped, oxynitride, aluminum oxide, or carbide.

The widths W_1 , W_2 , W_3 , W_{gap} , and/or W_t are determinable by one of ordinary skill in the art using, e.g., any suitable metrology tool.

In some embodiments, the first supporting member **120**, the second supporting member **130**, and the third supporting member **140** are rectangular, and the reference cross-sectional plane is positioned anywhere along the structure **100**. In some embodiments, the reference cross-sectional plane is positioned where the above-mentioned relationships among the widths W_1 , W_2 , W_3 , W_{gap} , and/or W_t are satisfied.

FIG. 2 is a flow chart of a method **200** of manufacturing a semiconductor structure (such as the semiconductor **300** depicted in FIG. 3G) in accordance with one or more embodiments. FIGS. 3A-3G are top views and corresponding cross-sectional views, taken from line B depicted in the top views, of a semiconductor structure **300** at various manufacturing stages in accordance with one or more embodiments. In some embodiments, the semiconductor structure **300** is usable as the structure **100** of FIG. 1A and FIG. 1B. It is understood that additional processes may be performed before, during, and/or after the method **200** depicted in FIG. 2, and that some other processes may only be briefly described herein. Others will be ascertainable to those having ordinary skill in the art.

As depicted in FIG. 2 and FIG. 3A, in operation **210**, a first supporting member **320**, a second supporting member **330**, and a third supporting member **340** are formed over a substrate **310**. The third supporting member **340** is farther from the first supporting member **320** than the second supporting member **330**. The substrate **310** corresponds to the substrate **110** in FIG. 1, and the first supporting member **320**, the second supporting member **330**, and the third supporting member **340** correspond to the first supporting member **120**, the second supporting member **130**, and the third supporting member **140** in FIG. 1. Therefore, the widths of and the spacing between the first supporting member **320**, the second supporting member **330**, and the third supporting member **340** have analogous relationships as described above for the first supporting member **120**, the second supporting member **130**, and the third supporting member **140** in FIG. 1.

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For example, the first supporting member **320** has a width (also denoted as W_1), the second supporting member **330** has a width (also denoted as W_2), and the third supporting member **340** has a width (also denoted as W_3). The first supporting member **320** and the second supporting member **330** are separated by a gap region **382** having a gap width (also denoted as W_{gap}). Also, the second supporting member **330** and the third supporting member **340** are separated by a trench region **384** having a trench width (also denoted as W_t).

In some embodiments, the gap region **382** is substantially free of any feature that interferes with formation of the photoresist layer **360** as depicted in FIG. 3B.

In some embodiments, each of the first supporting member **320**, the second supporting member **330**, and the third supporting member **340** independently comprises silicon dioxide or silicon nitride. In some embodiments, the first supporting member **320**, the second supporting member **330**, and the third supporting member **340** are formed by first forming a layer of supporting material followed by performing a patterning process to pattern the layer of supporting material. In some embodiments, the formation of the layer of supporting material includes performing a chemical vapor deposition (CVD), a physical vapor deposition (PVD), or a thermal oxidation process. In some embodiments, the patterning process for forming the first supporting member **320**, the second supporting member **330**, and the third supporting member **340** includes forming a patterned mask over the layer of supporting material and then partially removing the layer of material by a dry etching process or a wet etching process to form the supporting members **320**, **330**, and **340**.

In some embodiments, the third supporting member **340** is omitted. In some embodiments, one or more supporting members resembling the second or third supporting member **330** or **340** are formed to the left of the third supporting member **340** (i.e., the direction away from the first supporting member **320**).

As depicted in FIG. 2 and FIG. 3B, in operation **220**, a layer of material **350** is formed over the substrate **310** and covering upper surfaces and sidewalls of the first supporting member **320**, the second supporting member **330**, and the third supporting member **340** at least along the reference plane containing the line B and being perpendicular to an planar direction of the substrate **310**. The layer of material **350** includes a portion **352** over and covering the third supporting member **350**, a portion **354** over and covering the second supporting member **330**, and a portion **356** over and covering the first supporting member **320**. In some embodiments, the layer of material **350** includes any suitable materials for use in semiconductor manufacturing, such as metallic materials, semiconductor materials, dielectric materials, or hardmask materials. In some embodiments, the layer of material **350** comprises silicon nitride, silicon oxide, nitride with carbide doped, oxynitride, aluminum oxide, or carbide. In at least one embodiment, the layer of material **350** includes a conductive material such as polycrystalline silicon.

Returning to FIG. 2, in operation **230**, a photoresist layer **360** is formed over the layer of material **350**. The photoresist layer **360** has a first thickness T_1 over the first supporting member **320** and a second thickness T_2 over the second supporting member **330**. In some embodiments, W_1 , W_2 , and W_{gap} are chosen such that the photoresist layer **350** will be thicker over the first supporting member **320** than over the second supporting member **330** during the deposition or coating of the photoresist layer **360** over the first and second

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supporting members **320** and **330**. In some embodiments, the first thickness T_1 is greater than the second thickness T_2 . In some embodiments, the first thickness T_1 is at least 50 nm greater than the second thickness T_2 .

In some embodiments, the photoresist layer **360** includes a light-sensitive material usable to form a patterned coating on a surface. In some embodiments, the photoresist layer **360** includes negative photoresist materials or positive photoresist materials. In some embodiments, the photoresist layer **360** comprises acrylates, such as poly(methyl methacrylate); imides, such as poly(methyl glutarimide), phenols such as phenol formaldehyde resin, or epoxies such as SU-8. In some embodiments, the photoresist layer **360** comprises acrylate or methacrylate monomer.

As depicted in FIG. 2 and FIG. 3C, in operation **230**, a photoresist removal process is performed to expose an upper surface **372** of the portion **352** of the layer of material **350** over and covering the third supporting member **340**, without exposing upper surfaces **374** and **376** of other portions (such as the portions **354** and **356**) of the layer of material **350**. In some embodiments, the photoresist removal process includes partially exposing the photoresist layer **360** by using a lithographic process and subsequently removing the exposed portion of the photoresist layer **360** by using a photoresist development process.

As depicted in FIG. 2 and FIG. 3C, in operation **240**, the exposed portion **352** of the layer of material **350** is partially removed by performing an etching process. In at least one embodiment, the removal process in operation **240** is configured to fabricate a space **352'** (FIG. 3E) surrounding the third supporting member **340** having a thickness thinner than a space **352'** (FIG. 3E) surrounding the second supporting member **330** after the performance of operation **260** (FIG. 2). In some embodiments, the third supporting member **340** is omitted. In some embodiments, operations **230** and **240** are omitted, and thus the second supporting member **330** and the third supporting member **340** are identically processed. During the etching process, the photoresist layer **360** is used as a mask to protect the portions **374** and **376** of the layer of material **350** from being removed.

As depicted in FIG. 2 and FIG. 3D, in operation **250**, a photoresist removal process is performed to expose an upper surface **374** of the portion **354** of the layer of material **350** over and covering the second supporting member **330**, without exposing an upper surface **376** of the portion **356** of the layer of material **350**. In some embodiments, the photoresist removal process includes performing an ashing process for a predetermined period of time sufficient to remove the photoresist material over the second supporting member **330** and the portion **354** of the layer of material **350**.

Because of the thickness T_2 of the photoresist layer **360** over the second supporting member **330** is less than the thickness T_1 of the photoresist layer **360** over the first supporting member **330**, a film of photoresist material (being referred to as a photoresist film **362**) remains and covers at least the upper surface **376** of the portion **356** of the layer of material **350** over and covering the first supporting member **320**.

As depicted in FIG. 2 and FIG. 3E, in operation **260**, the exposed portions **352** and **354** of the layer of material **350** are partially removed by performing an etching process in order to form spacers **352'** and **354'** surrounding the second supporting member **330** and the third supporting member **340**. During the etching process, the photoresist film **362** is used, e.g., as a mask, to protect the portion **356** of the layer of material **350**. The operation **260** is configured to reveal upper surfaces of the second and third supporting members

330 and **340**. The operation **260** is also configured to form the spacers **352'** and **354'** each having a predetermined spacer width.

As depicted in FIG. 2 and FIG. 3F, in operation **270**, the photoresist film **376** is removed. Another photoresist layer **390** is deposited or coated over the first, second, and third supporting members **320**, **330**, and **340**. The photoresist layer **390** is subsequently patterned to form patterned photoresist feature **392** over the first supporting member and patterned photoresist feature **394** over the portion **356** of the layer of material **350** and the spacers **352'** and **354'**. The patterned photoresist features **392** and **394** are arranged to be masks for selectively etching the portion **356** of the layer of material **350** and the spacers **352'** and **354'**.

As depicted in FIG. 2 and FIG. 3G, in operation **280**, the portion **356** of the layer of material **350** and the spacers **352'** and **354'** are further patterned, by using the patterned photoresist features **392** and **394** as masks in an etching process, to form patterned features **357** over the first supporting member **320** and strips **358** on sidewalls of the second and third supporting members **330** and **340**. In some embodiments, the patterned features **357** correspond to the patterned feature **152** in FIG. 1, and the strips **358** correspond to the strips **154**, **155**, **156**, and **157** in FIG. 1.

In some embodiments, the patterned features **357** are further processed for forming relatively larger components and devices such as capacitors, antennas, or resistors in an IC chip. In some embodiments, the strips **358** are processed for forming relatively smaller components and devices such as electrodes or dummy gate electrodes of transistors in the same IC chip.

The structure **100** is subject to multiple uses. In some embodiments, the structure **100** is an intermediate product used to form an integrated circuit chip. The method **200** is subject to many applications. In some embodiments, the method **200** constitutes a portion of a manufacturing process for making an integrated circuit chip.

One aspect of this description relates to a method of making a structure. The method includes forming a first supporting member over a substrate, the first supporting member comprising a first material and having a first width defined along a reference plane. The method further includes forming a second supporting member over the substrate, the second supporting member having a second width defined along the reference plane, and the first supporting member and the second supporting member being separated by a gap region. The first width being at least 10 times the second width, and a gap width of the gap region being from 5 to 30 times the second width.

Another aspect of this description relates to a method of making a structure. The method includes forming a first supporting member over a substrate, wherein the first supporting member has a first width. The method further includes forming a second supporting member over the substrate, wherein the second supporting member has a second width, and the second supporting member is spaced from the first supporting member by a gap width. The method further includes forming a material layer over the first supporting member and the second supporting member. The method further includes forming a photoresist layer over the material layer, wherein a thickness of the photoresist layer above the first supporting member is greater than a thickness of the photoresist layer above the second supporting member.

Still another aspect of this description relates to a method of making a structure. The method includes forming a first supporting member over a substrate, wherein the first sup-

porting member has a first width. The method further includes forming a second supporting member over the substrate, wherein the second supporting member has a second width, and the second width is less than the first width. The method further includes forming a third supporting member over the substrate, wherein the third supporting member has a third width, the second supporting member is between the first supporting member and the third supporting member, and a ratio of the second width to the third width ranges from about 0.8 to about 1.2. The method further includes forming a trench between the second supporting member and the third supporting member, wherein a ratio of a width of the trench to the second width ranges from about 2.0 to about 3.0.

The foregoing outlines features of several embodiments so that those skilled in the art may better understand the aspects of the present disclosure. Those skilled in the art should appreciate that they may readily use the present disclosure as a basis for designing or modifying other processes and structures for carrying out the same purposes and/or achieving the same advantages of the embodiments introduced herein. Those skilled in the art should also realize that such equivalent constructions do not depart from the spirit and scope of the present disclosure, and that they may make various changes, substitutions, and alterations herein without departing from the spirit and scope of the present disclosure.

What is claimed is:

1. A method of making a structure, the method comprising:

forming a first supporting member over a substrate, the first supporting member comprising a first material and having a first width defined along a reference plane; forming a second supporting member over the substrate, the second supporting member having a second width defined along the reference plane, and the first supporting member and the second supporting member being separated by a gap region; and

forming a third supporting member over the substrate, the third supporting member having a third width defined along the reference plane, and the third supporting member being farther from the first supporting member than the second supporting member,

the first width being at least 10 times the second width, and a gap width of the gap region is from 5 to 30 times the second width.

2. The method of claim 1, further comprising:

forming a layer of material over the substrate and covering, along the reference plane, the first supporting member and the second supporting member; and

forming a photoresist layer over the layer of material, the photoresist layer having a first thickness over the first supporting member and a second thickness over the second supporting member, and the first thickness is greater than the second thickness.

3. The method of claim 2, further comprising performing a photoresist removal process to expose an upper surface of the layer of material over the second supporting member without exposing another upper surface of the layer of material over the first supporting member.

4. The method of claim 3, further comprising patterning the layer of material to form strips on sidewalls of the second supporting member.

5. The method of claim 4, further comprising removing the second supporting member after the formation of the strips.

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6. The method of claim 3, further comprising forming another patterned photoresist layer over the first supporting member.

7. The method of claim 1, wherein the layer of material being formed over the third supporting member, and the method further comprising:

performing a photoresist removal process to expose an upper surface of the layer of material over the third supporting member without exposing other upper surfaces of the layer of material over the first supporting member and the second supporting member; and partially removing the layer of material over the third supporting member.

8. The method of claim 1, wherein the second width ranges from 30 nm to 90 nm, the first width ranges from 300 nm to 900 nm, and the gap width ranges from 200 nm to 1,000 nm.

9. A method of making a structure, the method comprising:

forming a first supporting member over a substrate, wherein the first supporting member has a first width; forming a second supporting member over the substrate, wherein the second supporting member has a second width, and the second supporting member is spaced from the first supporting member by a gap width; forming a material layer over the first supporting member and the second supporting member; and forming a photoresist layer over the material layer, wherein a thickness of the photoresist layer above the first supporting member is greater than a thickness of the photoresist layer above the second supporting member.

10. The method of claim 9, further comprising removing a portion of the photoresist above the second supporting member, wherein removing the portion of the photoresist above the second supporting member comprises maintaining the photoresist layer above the first supporting member.

11. The method of claim 9, further comprising patterning the material layer to form strips of material along sidewalls of the second supporting member.

12. The method of claim 11, wherein forming the strips of material comprises forming an electrode of a transistor or a dummy electrode of a transistor.

13. The method of claim 9, further comprising patterning the material layer to form at least one patterned feature over a top surface of the first supporting member.

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14. The method of claim 13, wherein forming the at least one patterned feature comprises forming a capacitor, an antenna or a resistor.

15. The method of claim 9, wherein forming the material layer comprises forming the material layer comprising a conductive material.

16. A method of making a structure, the method comprising:

forming a first supporting member over a substrate, wherein the first supporting member has a first width; forming a second supporting member over the substrate, wherein the second supporting member has a second width, and the second width is less than the first width; forming a third supporting member over the substrate, wherein the third supporting member has a third width, the second supporting member is between the first supporting member and the third supporting member, and a ratio of the second width to the third width ranges from about 0.8 to about 1.2; and

forming a trench between the second supporting member and the third supporting member, wherein a ratio of a width of the trench to the second width ranges from about 2.0 to about 3.0.

17. The method of claim 16, further comprising forming at least one conductive feature over the first supporting member.

18. The method of claim 17, wherein forming the at least one conductive feature comprises:

forming a conductive layer over the first supporting member, the second supporting member and the third supporting member; protecting the conductive layer adjacent to the second supporting member and the conductive layer adjacent to the third supporting member; and patterning the conductive layer over the first supporting member while the conductive layer adjacent to the second supporting member and the third supporting member is protected.

19. The method of claim 16, further comprising forming conductive strips along opposite sidewalls of at least one of the second supporting member or the third supporting member.

20. The method of claim 1, wherein forming the third supporting member comprises forming the third supporting member wherein a ratio of the second width to the third width ranges from about 0.8 to about 1.2.

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